

WHAT IS CLAIMED IS:

1. An IC chip package comprising:

a substrate having a top side, a bottom side, and a plurality of conductive pads arranged on the top side;

a chip fixedly mounted on the top side of said substrate and having a plurality of conductive pads;

a plurality of bonding wires respectively electrically connected between the conductive pads of said substrate and the conductive pads of said chip;

adhesive means provided on the top side of said substrate around the border thereof;

a cover adapted for covering said substrate; and

a spacer connected between said substrate and said cover to keep said cover from said substrate at a distance.

2. The IC chip package as claimed in claim 1, wherein said adhesive means is applied to the border of the top side of said substrate and covered on the connecting area between said bonding wires and the conductive pads at the top side of said substrate.

3. The IC chip package as claimed in claim 1, wherein said cover is adhered to said adhesive means.

4. The IC chip package as claimed in claim 1, wherein said spacer comprises at least one column respectively fixedly connected between said substrate and said cover.

5. The IC chip package as claimed in claim 4, wherein the top side of said substrate has at least one recessed locating hole adapted to receive said at least one column.

6. The IC chip package as claimed in claim 4, wherein said substrate comprises at least one locating through hole extended through the top and bottom sides thereof, and the at least one column of said spacer is respectively inserted through the at least one locating hole of said substrate and exposed to the outside of the bottom side of said substrate.

7. The IC chip package as claimed in claim 1, wherein said spacer is comprised of an open frame fixedly connected between said substrate and said cover.

8. The IC chip package as claimed in claim 7, wherein said open frame has a recessed portion facing said substrate for receiving said adhesive means.

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9. The IC chip package as claimed in claim 1, wherein said cover is made of transparent material.

10. The IC chip package as claimed in claim 1, wherein said cover has a through hole aimed at said chip, and at least one lens respectively sealed in the through hole.

11. The IC chip package as claimed in claim 1, wherein said cover comprises a screw hole extended through the top and bottom sides thereof corresponding in location to said chip, and a lens unit mounted in said screw hole, said lens unit comprising a barrel threaded into said screw hole and at least one lens sealed in said barrel.

12. The IC chip package as claimed in claim 1, wherein said substrate is made of the materials selected from the group consisting of reinforced plastics, glass fibers, and ceramics.

13. The IC chip package as claimed in claim 1, wherein said adhesive means is selected from the group consisting of silicones, epoxies, acrylics, polyamides, and glass.

14. The IC chip package as claimed in claim 1, wherein said adhesive means is a double-sided adhesive tape.

15. The IC chip package as claimed in claim 1, wherein said

substrate further comprises a plurality of electronic elements mounted on the top side thereof and electrically connected to the conductive pads at the top side of said substrate.

16. The IC chip package as claimed in claim 1 further comprising a connecting device adapted to electrically connect the conductive pads of said substrate to an external object outside said substrate.

17. The IC chip package as claimed in claim 16, wherein said connecting device comprises a plurality of plated through holes disposed in the periphery of said substrate and adapted to connect the conductive pads at the top side of said substrate to the bottom side of said substrate.

18. The IC chip package as claimed in claim 16, wherein said connecting device comprises a plurality of plated through holes electrically connected between the conductive pads at the top side of said substrate and the bottom side of said substrate, and a plurality of solder balls provided at the bottom side of said substrate and respectively electrically connected to the through holes of said connecting device.

19. The IC chip package as claimed in claim 16, wherein said connecting device comprises a plurality of metal leads, said metal leads each having one end electrically connected to the conductive pads at the top side of said substrate and an opposite end extended to the outside of said substrate and bent into a predetermined shape.